

*CLAIM AMENDMENTS*

1. (Currently Amended) A burn-in test adapter, to which an assembly substrate, on which a plurality of semiconductor chips, each having a terminal receiving a burn-in test waveform, are arranged, is detachably attached, comprising:

~~a wiring provided in such a manner that for, when the assembly substrate is attached to the burn-in test adapter, the wiring makes an making electrical contact with the terminal terminals of each of the semiconductor chips on the assembly substrate; and~~

~~a burn-in test terminal electrically connected to the wiring and receiving the burn-in test waveform.~~

2. (Currently Amended) The burn-in test adapter according to claim 1, further comprising a burn-in test waveform generation circuit that increases the number of the burn-in test waveforms, and ~~that is provided located~~ on the wiring at positions that correspond to positions of the individual semiconductor chips when the assembly substrate is attached to the burn-in test adapter.

3. (Currently Amended) The burn-in test adapter according to claim 1, wherein the burn-in test adapter is rectangular and has four sides, and the burn-in test terminal is ~~arranged located~~ on one of the four sides of the burn-in test adapter.

4. (Currently Amended) A burn-in test apparatus comprising:

a burn-in test adapter, to which an assembly substrate, on which a plurality of semiconductor chips, each having a terminal receiving a burn-in test waveform, are arranged, is detachably attached, the burn-in test adapter including:

~~a first wiring provided in such a manner that for, when the assembly substrate is attached to the burn-in test adapter, the wiring makes making an electrical contact with the terminal terminals of each of the semiconductor chips on the assembly substrate; and~~

~~a burn-in test terminal that is electrically connected to the first wiring and receives receiving the burn-in test waveform, wherein the burn-in test adapter is rectangular and has four sides, and the burn-in test terminal is arranged located on one of the four sides of the burn-in test adapter;~~

~~a socket that holds the burn-in test adapter at the side on which the burn-in test terminal is arranged located and that is electrically connected to the burn-in test terminal; and~~

~~a burn-in board that holds the socket and that includes a second wiring that is electrically connected to the socket, wherein the second wiring receives the burn-in test waveform.~~

5. (Currently Amended) The burn-in test apparatus according to claim 4, wherein including a plurality of the sockets are provided in plurality.

6. (Currently Amended) A burn-in test adapter, to which an assembly substrate, on which a plurality of semiconductor chips, each having a chip-side terminal for receiving a burn-in test waveform, are arranged, is detachably attached, comprising:

an adapter-side terminal corresponding to each chip-side terminal, wherein the adapter-side terminal is arranged at such a position located so that, when the assembly substrate is attached to the burn-in test adapter, the adapter-side terminal makes ~~an~~ electrical contact with the corresponding chip-side terminal;

a signal receiving terminal that receives the burn-in test waveform; and

~~a~~ wiring that electrically connects the adapter-side terminal to the signal receiving terminal.